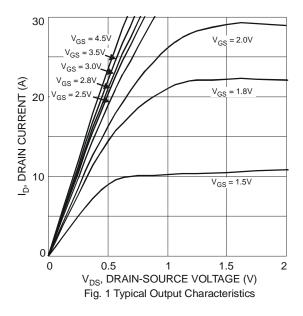


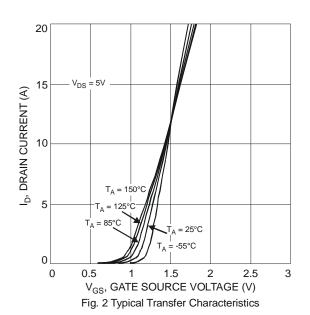
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	-	-	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	0.5	-	0.9	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
		-	19	25		$V_{GS} = 4.5V, I_D = 8.2A$
Static Drain-Source On-Resistance	R _{DS (ON)}		22	29		$V_{GS} = 2.5V, I_D = 3.3A$
	ì í		28	37		$V_{GS} = 1.8V, I_D = 2.0A$
Forward Transfer Admittance	Y _{fs}	-	7	-	S	$V_{DS} = 10V, I_D = 4A$
Diodes Forward Voltage	V_{SD}	-	0.7	0.9	V	Is = 2.25A, V _{GS} = 0V
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	C _{iss}	-	841	-	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz
Output Capacitance	Coss	-	88	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	81	-	pF	
Gate Resistance	R_g	-	1.24	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
SWITCHING CHARACTERISTICS						
Total Gate Charge	Q_{g}	-	9.6	-	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_D = 8.2A$
Gate-Source Charge	Q_{gs}	-	1.4	-	nC	
Gate-Drain Charge	Q_{gd}	-	2.1	-	nC	
Turn-On Delay Time	t _{D(on)}	-	7.8	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_{L} = 10\Omega, R_{G} = 6\Omega$
Turn-On Rise Time	t _r	-	21.1	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	38.6	-	ns	
Turn-Off Fall Time	t _f	-	10.1	-	ns	

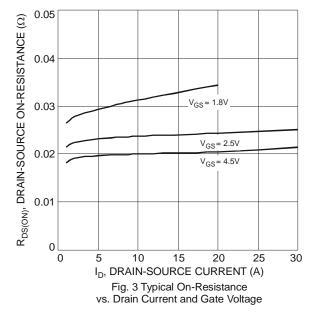
Notes:

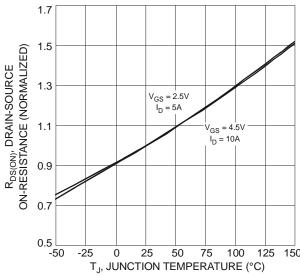
- 5. Short duration pulse test used to minimize self-heating effects.6. Guaranteed by design. Not subject to production testing.

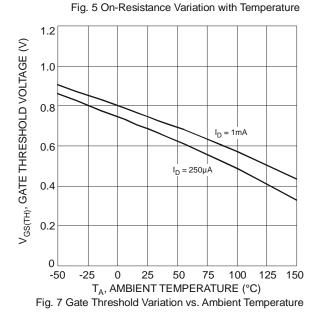












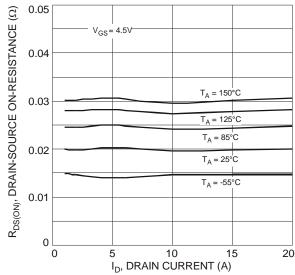


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

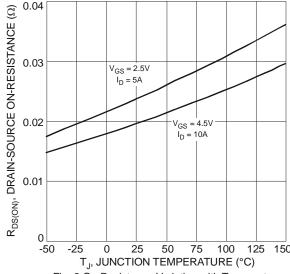
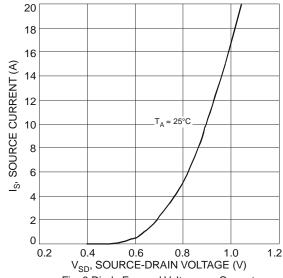
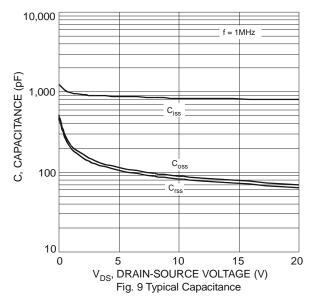


Fig. 6 On-Resistance Variation with Temperature







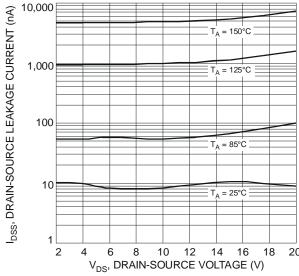


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

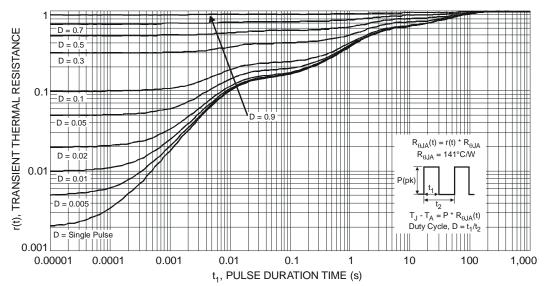


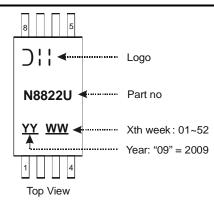
Fig. 11 Transient Thermal Response

Ordering Information (Note 7)

Part Number	Case	Packaging
DMG8822UTS-13	TSSOP-8L	2500 / Tape & Reel

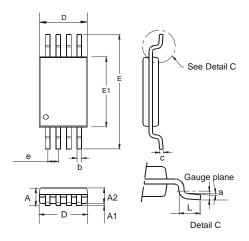
Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



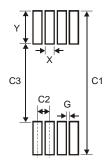


Package Outline Dimensions



TSSOP-8L						
Dim	Min	Max	Тур			
а	0.09	-	-			
Α	-	1.20	-			
A1	0.05	0.15	-			
A2	0.825	1.025	0.925			
b	0.19	0.30	-			
С	0.09	0.20	-			
D	2.90	3.10	3.025			
е	_	-	0.65			
Е	_	_	6.40			
E1	4.30	4.50	4.425			
L	0.45	0.75	0.60			
All Dimensions in mm						

Suggested Pad Layout



Dimensions	Value (in mm)
Х	0.45
Y	1.78
C1	7.72
C2	0.65
C3	4.16
G	0.20



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